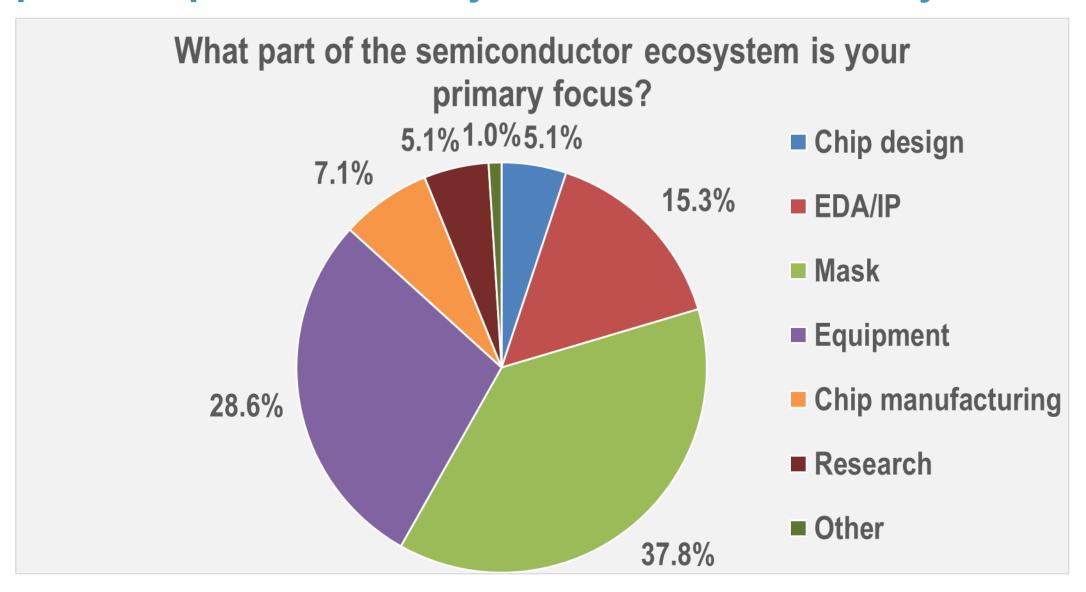
Our 6th Annual Perceptions Survey – 2017 40 companies represented this year - 10 more than last year

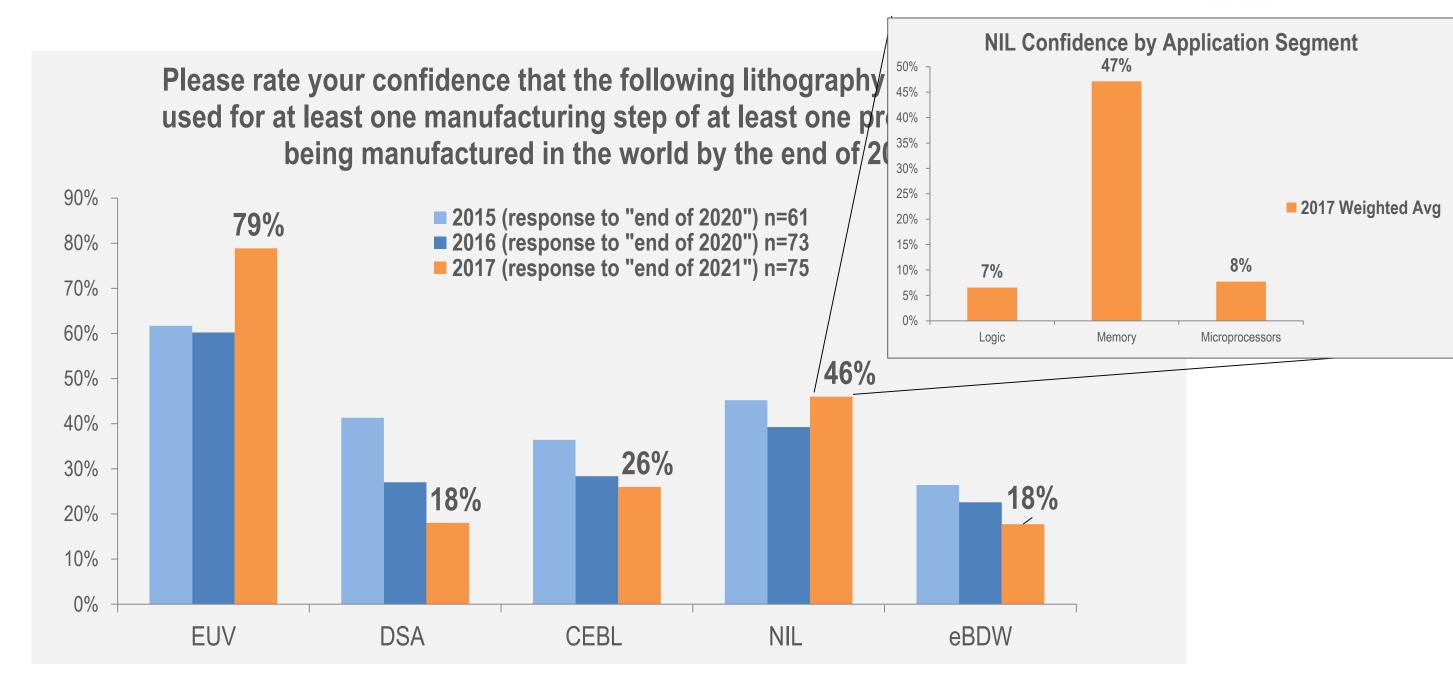




Thank you to the 75 luminaries and members for your responses!

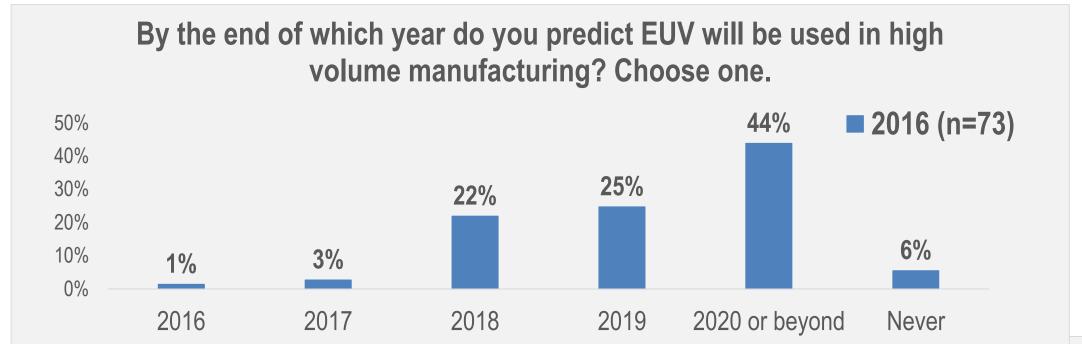
EUV Confidence Reflected in Survey Results NIL confidence remains driven by Memory applications

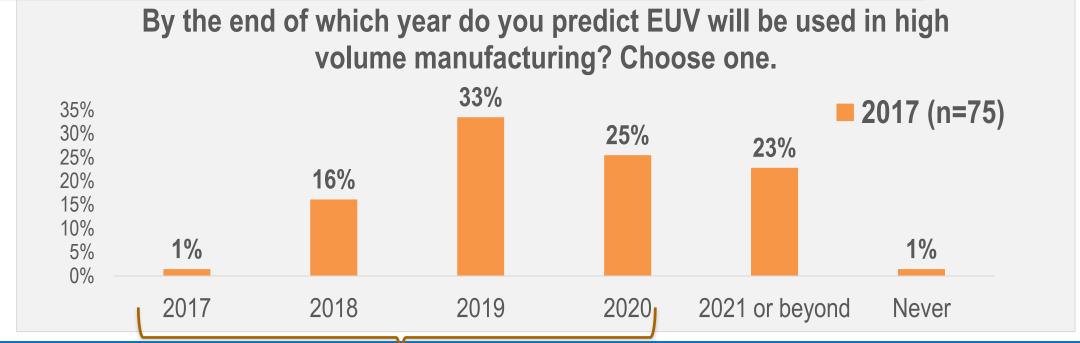




75% Predict EUV in HVM by End of 2020

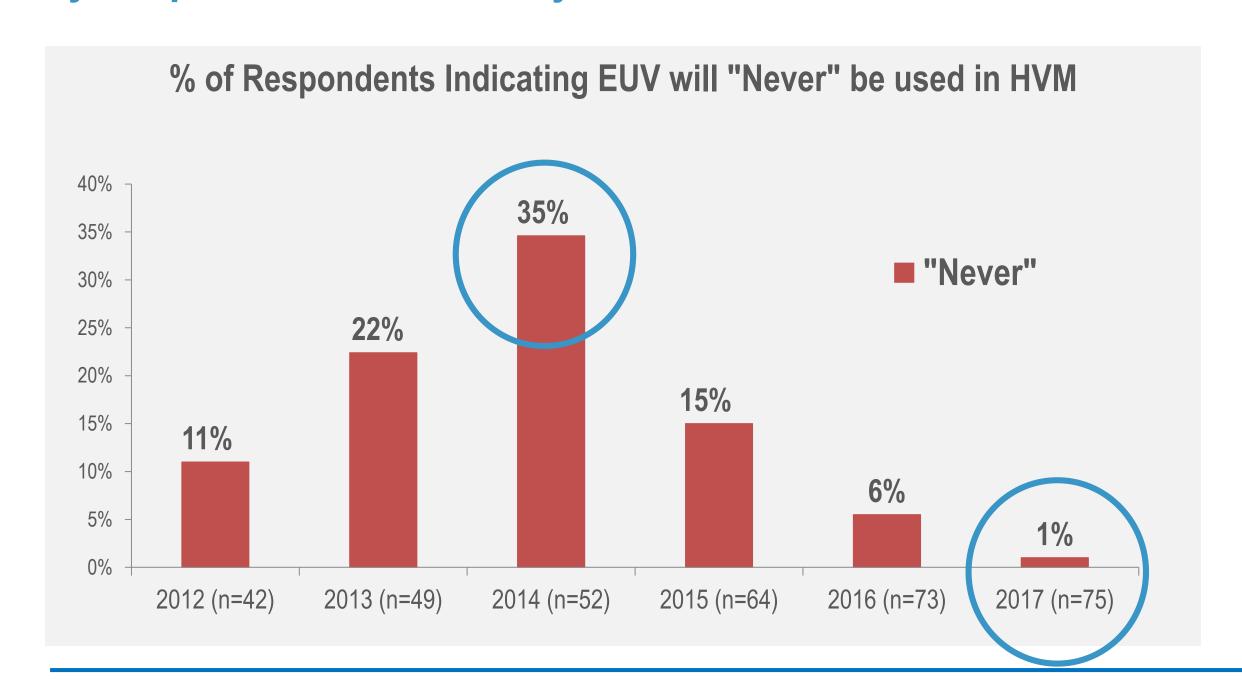






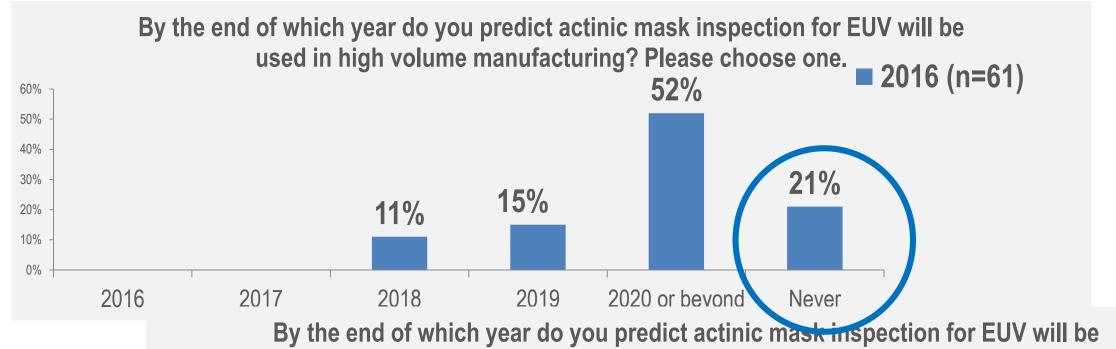
EUV Pessimism Now Negligible Only 1% predict "Never" this year vs 35% in 2014

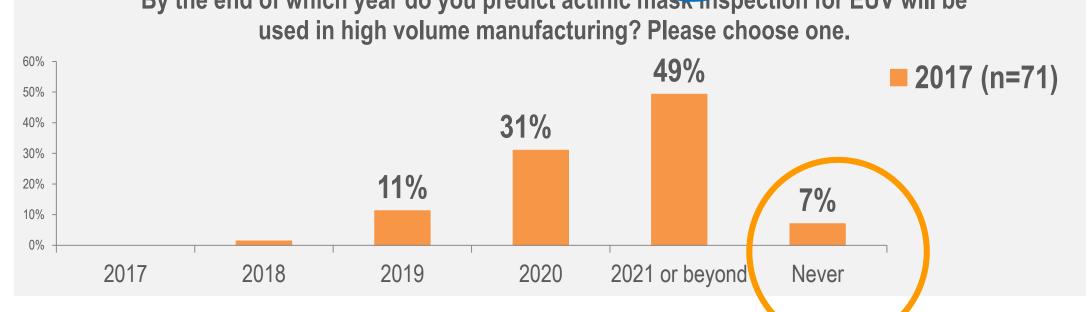




Actinic Inspection Predictions More Hopeful Only 7% predict "Never" this year vs 21% in 2016

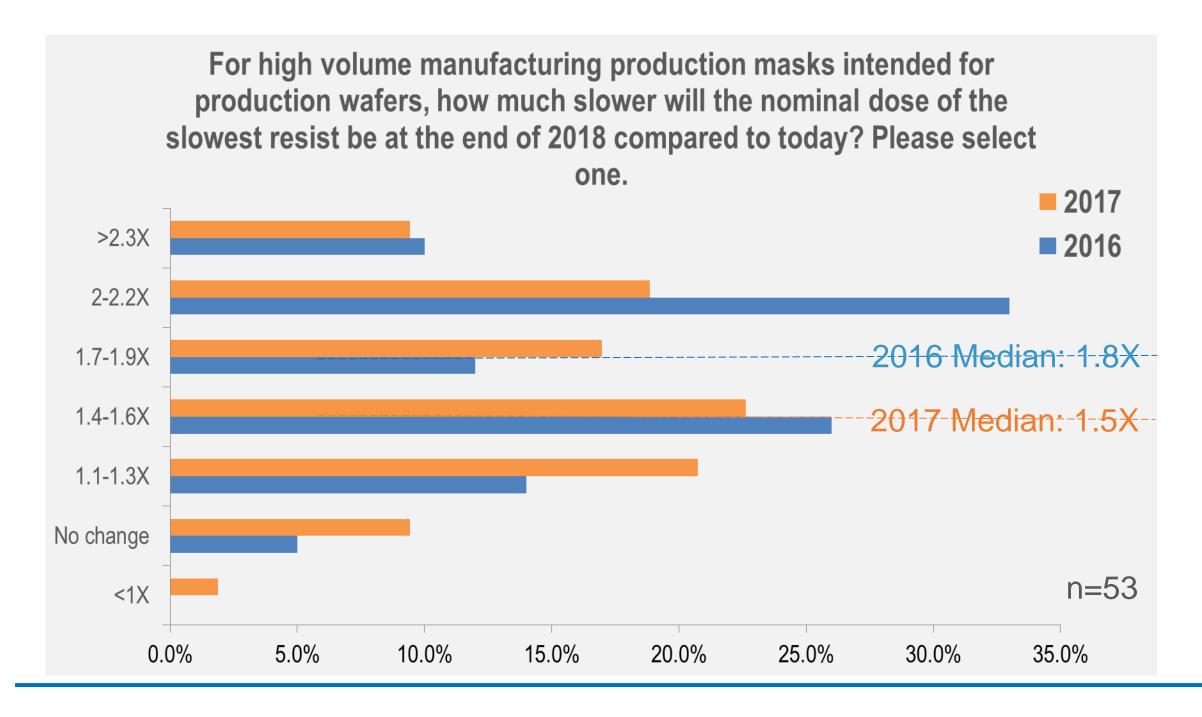






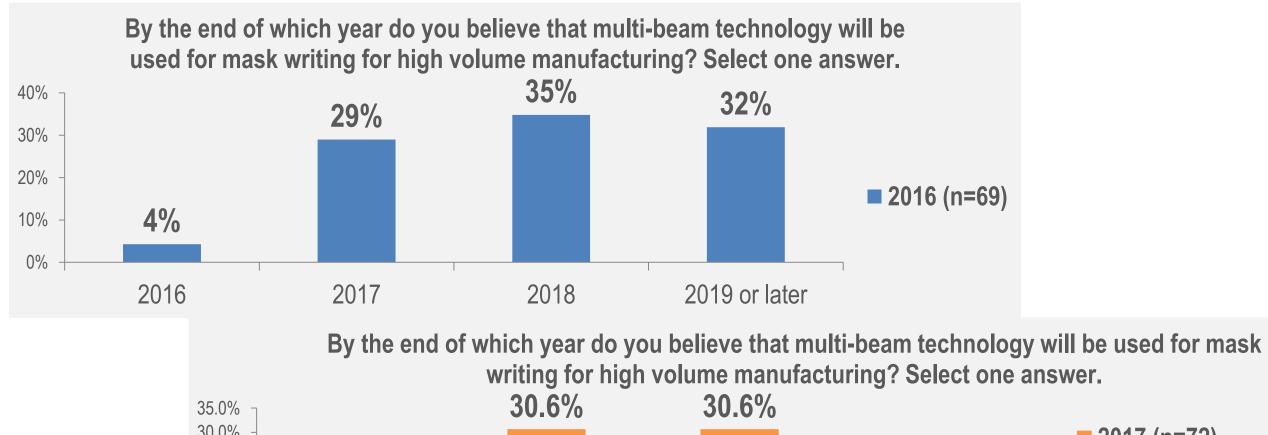
Consistent View: Slower Mask Resists Predicted

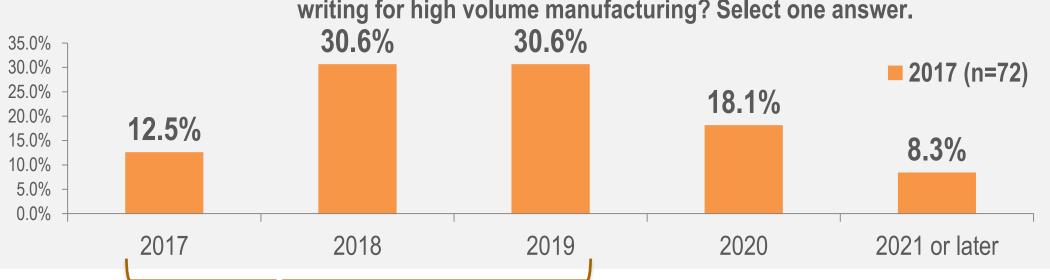




74% Say Multi-beam HVM by end of 2019 Predictions extend 2016 survey* results by >10 months

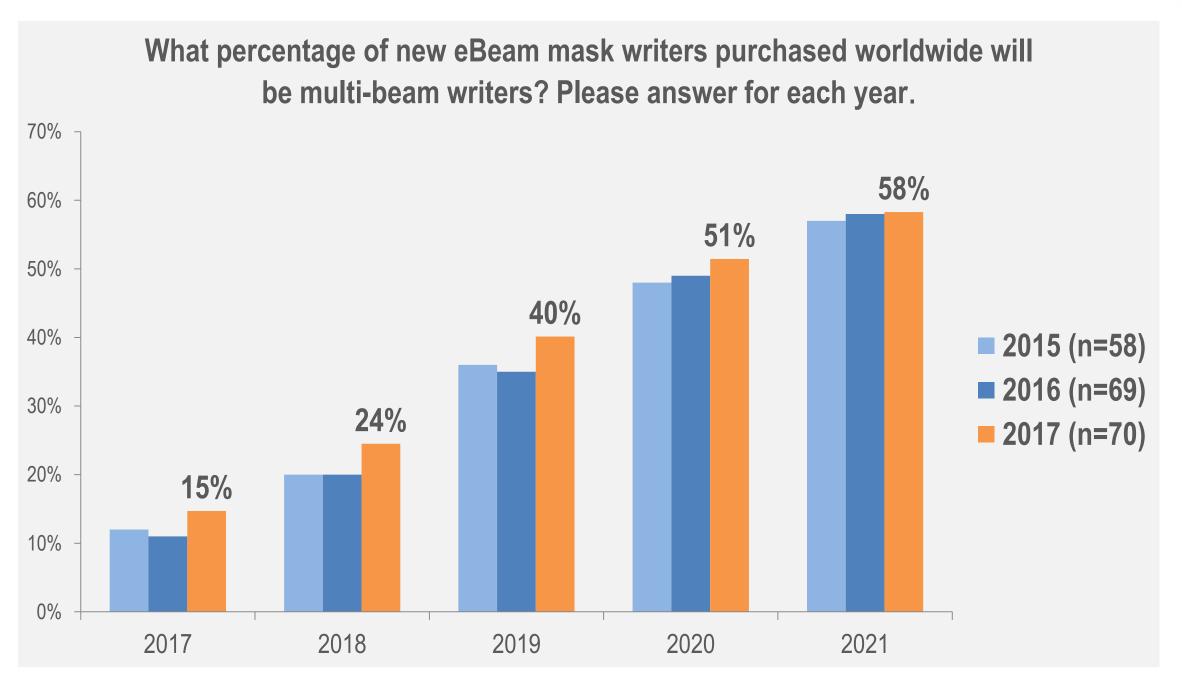






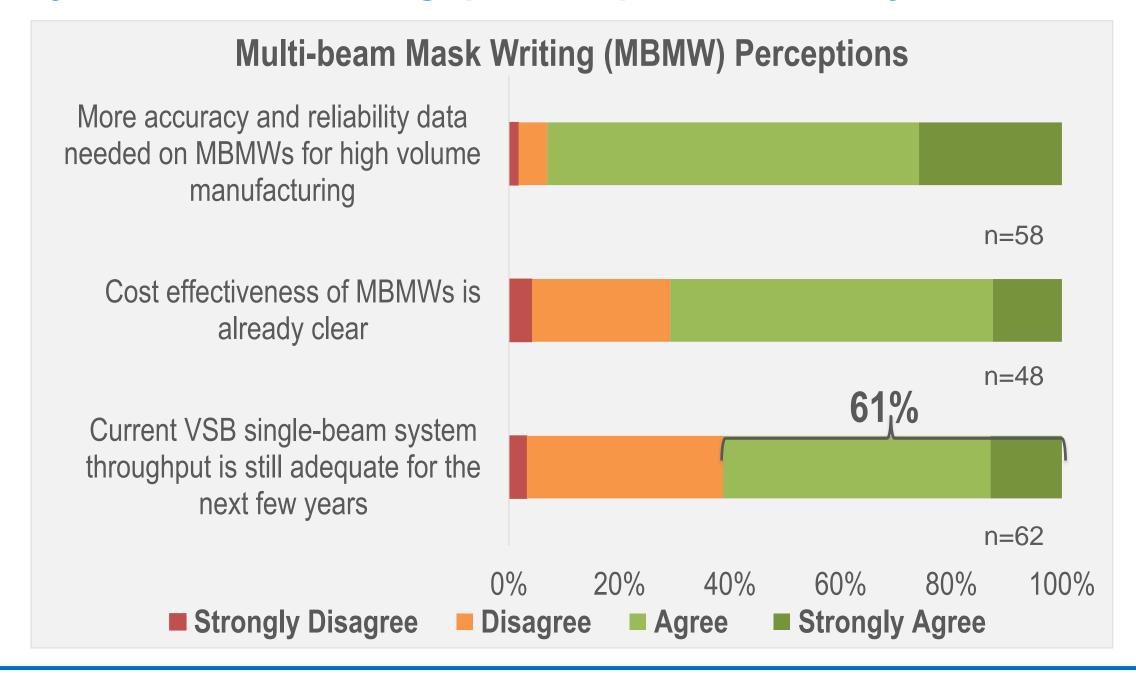
Yet Multi-beam Purchasing Predictions Increased





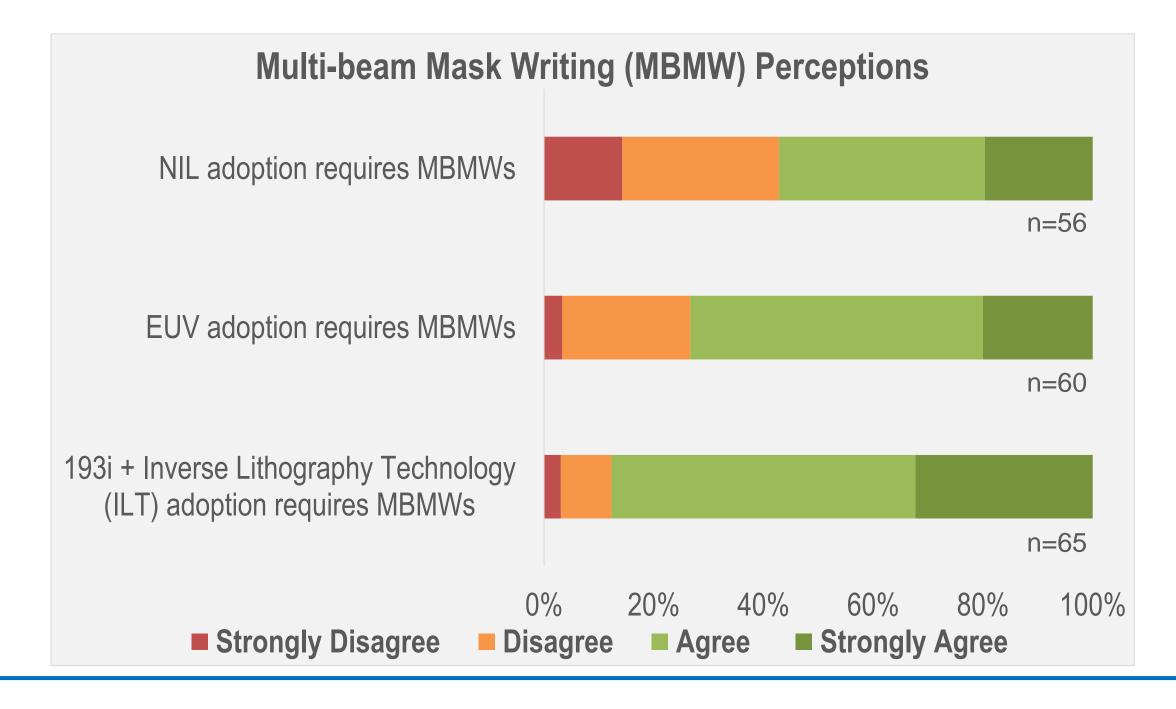
Multi-beam Perceptions Reflect Early Days 61% say VSB eBeam throughput adequate next few years





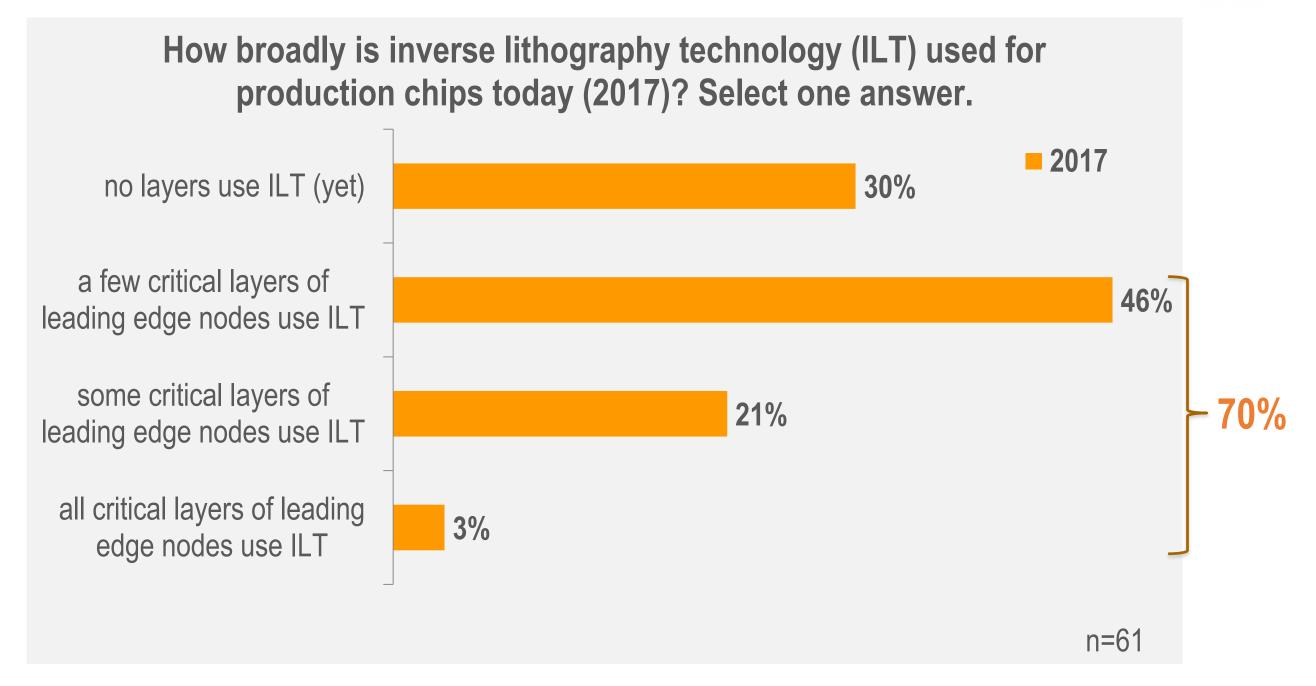
Majority Perceive MBMW Required for ILT & EUV





70% Think ILT Usage Starting at Leading Edge

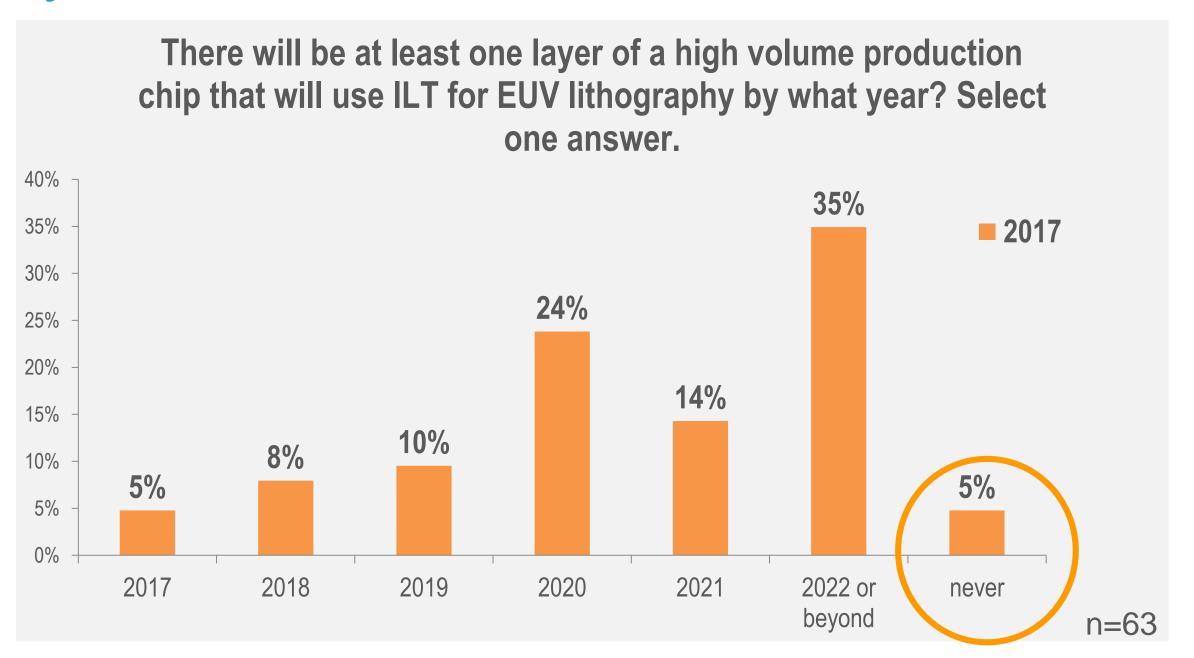




ILT Predicted to be a Future Need for EUV

BeamInitiative

Only 5% said "Never"



A New Era Has Begun



- EUV greater confidence and optimism reflected throughout survey
- Multi-beam expectations remain high while timeframe has shifted
- VSB and multi-beam mask writers predicted to co-exist
- ILT believed to be used in a few layers of many leading-edge chips



Thank you to those who participated in the survey!

Feedback and questions for future surveys welcome – send to jan@williscalibra.com